| ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES International and Pan- | C. Bannockb | urn. Illinois. A | ll rights reserved untions. | under both | This docume level parts, t | ent is a declara | tion of the s encompass | substances es all lowe | within the r level ma | manufacture terials for wh | er listed ite nich the ma | m. Note: nufacture | if the item is an as er has engineering | sembly with low responsibility. |
|---|--|--------------------------|-----------------------------|-------------------------|--|--|-------------------------------|---------------------------|--------------------------|---------------------------------|------------------------------|-----------------------|--|------------------------------------|
| | | | | Form Type Distribute | * | Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi | | | | | als and Mfg Information | | | |
| Supplier Information | | | | | | | | | | | | | | |
| Company name* Compar | | | ompany unique ID | | | Unique ID Authority | | | | | Response Date* | | | |
| onsemi | | | | | | | | | | | 2025-08-01 | | | |
| Contact Name | ntact Name Title - Contact | | | | | Phone - Contact* | | | | | Email - Contact* | | | |
| Product-Env-Stewards Product Enviro | | | viro Compliance | | | NA | | | | Product-Env-Stewards@onsemi.com | | | | |
| Authorized Representative* Title - Represen | | | sentative | | | Phone - Representative* | | | | Email - Representative* | | | | |
| Product-Env-Stewards Product Env | | | ct Enviro Compliance | | | NA | | | | Product-Env-Stewards@onsemi.com | | | | |
| Requester Item Number | Mfr Item Number | | mber Mfr Item Name | | | Effective Da | te Version Manufacturing Site | | ring Site | W | eight* | UOM | Unit Type | |
| | NTMD3 | NTMD3P03R2G PFET SO8 30V | | 3.05A 85MOHM | | 2025-08-01 | | | PH1 | | 7 | .99 | mg | Each |
| Manufacturing Proccess Informati | on | | | | | | | | | | | | | |
| Terminal Plating / Grid Array Mat | ng / Grid Array Material Terminal Base Alloy | | | J-STD-020 MSI | L Rating Peak Process Body Temperature Max T | | | | ime at Peak | Temperatu | re Num | ber of Reflow Cyc | les | |
| Matte Tin (Sn) - annealed CU Alloy | | | 1 | | 260 | | С | 30 | | second | s 3 | | | |
| omments | | | | | | | | | | | | | | |
| vel 1 - maximum time at peak temperatur | e during sol | dering is 10-3 | 0 seconds | | | | | | | | | | | |
| or more information regarding material c | omposition | please refer to | page 3 | | | | | | | | | | | |

| RoHS Material Composition Declaration | | | | Declaration Type * | Detailed | | | | | | | |
|--|--|--|---|---|---|--|--|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS Directive 2011/65/EU | RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP). | | | | | | | | | | | |
| cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a | ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the | henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies | RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform | ce of its products with European Union membe | ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of | | | | | | | |
| RoHS Declaration * 1 - Item(s) | does not contain RoHS restricted substa | ances per the definitio | on above | Supplier Acceptance | * Accepted | | | | | | | |
| Exemption: If the declared item does not con applicable exemptions. | ntain RoHS restricted substances per | the definition above | except for defined RoHS exempti | ons, then select the corresponding response i | n the RoHS Declaration above and choose all | | | | | | | |
| Exemption List Version | EL-2011/534/EU | | | | | | | | | | | |
| Declaration Signature | | | | | | | | | | | | |
| Instructions: Complete all of the required fin Requester) and click on Submit Form to have | elds on all pages of this form. Select the form returned to the Requester | he "Accepted" on th | e Supplier Acceptance drop-down | . This will display the signature area. Digital | lly sign the declaration (if required by the | | | | | | | |
| Supplier Digital Signature Ra | stislav Drska | Le | | | | | | | | | | |

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| | cable [E] enter the weigh | | | ance category (JIG or Requester) or enter [F] Optionally enter the positive (+) and | | | | |
|----------------------|---------------------------|-----------------|----------|--|------------------|--------|---------|-----------------|
| Homogeneous Material | Weight | Unit of Measure | Level | Substance | CAS | Exempt | Weight | Unit of Measure |
| Die | 1.33 | mg | Supplier | Silicon (Si) | 7440-21-3 | | 1.33 | mg |
| Die Attach | 2.4 | mg | Supplier | Silver (Ag) | 7440-22-4 | | 1.8 | mg |
| | | | Supplier | Epoxy resins | 129915-35-1 | | 0.6 | mg |
| Lead Frame | 37.61 | mg | Supplier | Silver (Ag) | 7440-22-4 | | 0.7898 | mg |
| | | | Supplier | Zinc (Zn) | 7440-66-6 | | 0.0752 | mg |
| | | | Supplier | Iron (Fe) | 7439-89-6 | | 0.9403 | mg |
| | | | Supplier | Copper (Cu) | 7440-50-8 | | 35.8047 | mg |
| Mold Compound-Black | 28.58 | mg | | Epoxy Phenol Resin | proprietary data | | 3.0009 | mg |
| | | | Supplier | Fused Silica (SiO2) | 60676-86-0 | | 25.5791 | mg |
| Plating | 1.89 | mg | Supplier | Tin (Sn) | 7440-31-5 | | 1.89 | mg |
| Wire Bond - Cu | 0.18 | mg | Supplier | Copper (Cu) | 7440-50-8 | | 0.18 | mg |